

**HIGH CMR, HIGH-SPEED 10 Mbps, TOTEM POLE OUTPUT TYPE  
5-PIN SOP PHOTOCOUPLER**

–NEPOC Series–

**DESCRIPTION**

The PS9711 is an optically coupled high-speed, totem pole output isolator containing a GaAlAs LED on the input side and a photodiode and a signal processing circuit on the output side on one chip.

**FEATURES**

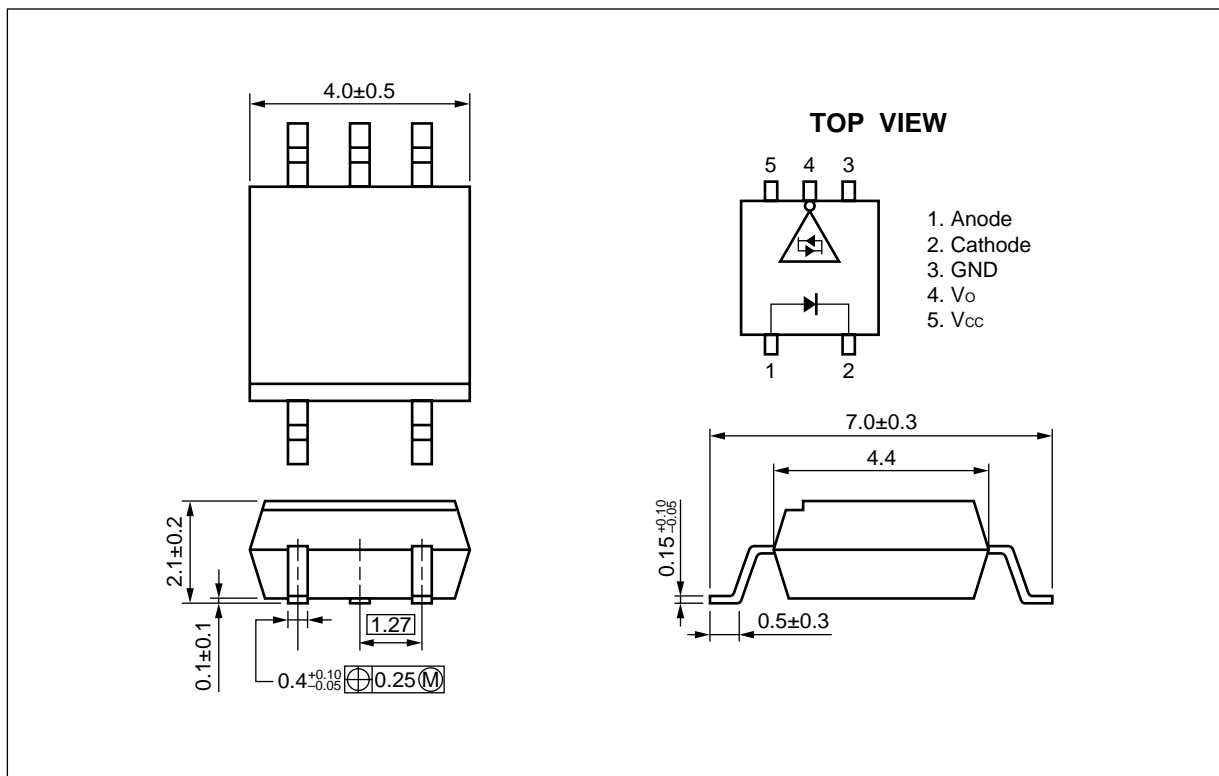
- High common mode transient immunity ( $CM_H$ ,  $CM_L = \pm 10 \text{ kV}/\mu\text{s}$  TYP.)
- Small and thin package (5-pin SOP)
- High-speed response ( $t_{PHL} = 30 \text{ ns}$ ,  $t_{PLH} = 35 \text{ ns}$  TYP.)
- Pulse width distortion ( $|t_{PHL} - t_{PLH}| = 7 \text{ ns}$  TYP.)
- Totem pole output (No pull-up resistor required)
- ★ • Ordering number of taping product: PS9711-F3, F4: 3 500 pcs/reel
- ★ • Safety standards
  - UL approved: File No. E72422 (S)
  - BSI approved (BS415, BS7002) : No. 8387
  - VDE0884 approved (Option)

**APPLICATIONS**

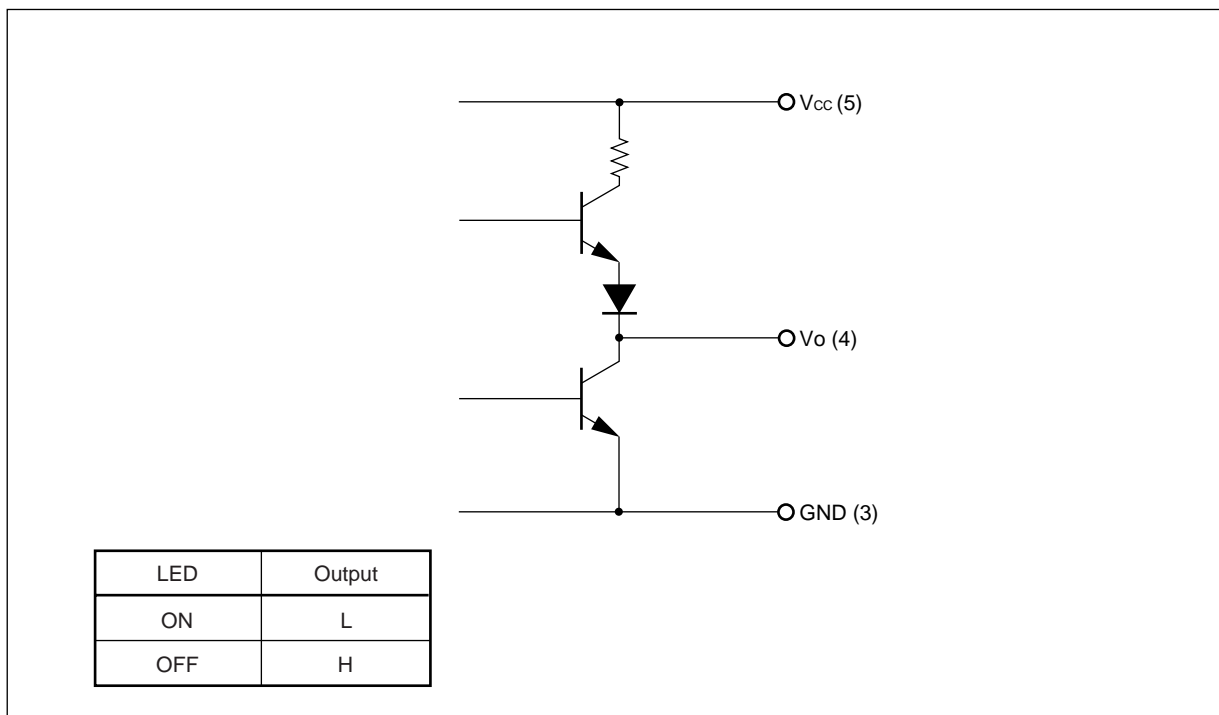
- Computer and peripheral manufactures
- Measurement equipment
- PDP

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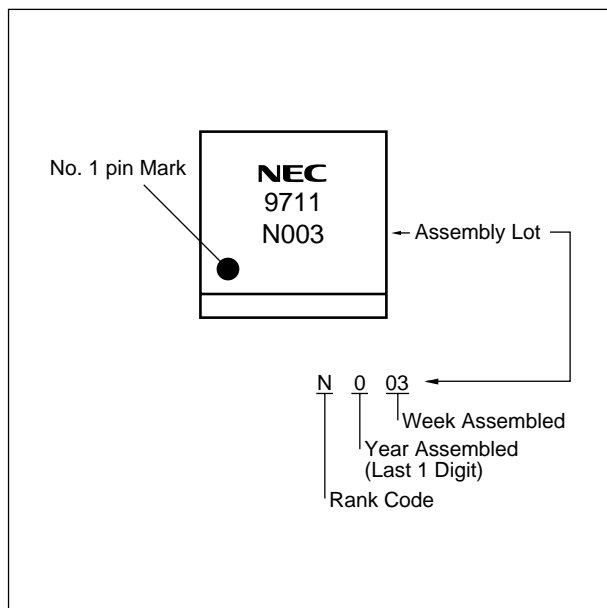
PACKAGE DIMENSIONS (UNIT: mm)



INTERNAL OUTPUT CIRCUIT



★ MARKING EXAMPLE



★ ORDERING INFORMATION

Part Number		Package	Packing Style	Application Part Number <sup>*1</sup>
Standard Products	VDE0884 Approved Products (Option)			
PS9711	PS9711-V	5-pin SOP	Magazine case 100 pcs	PS9711
PS9711-F3	PS9711-V-F3		Embossed tape 3 500 pcs/reel	
PS9711-F4	PS9711-V-F4			

\*1 For the application of the Safety Standard, following part number should be used.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)**

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Parameter		Symbol	Ratings	Unit
Diode	Forward Current	I <sub>F</sub>	30	mA
	Reverse Voltage	V <sub>R</sub>	5	V
Detector	Supply Voltage	V <sub>CC</sub>	7	V
	Output Voltage	V <sub>O</sub>	7	V
	High Level Output Current <sup>*1</sup>	I <sub>OH</sub>	−5	mA
	Low Level Output Current <sup>*1</sup>	I <sub>OL</sub>	13	mA
	Power Dissipation <sup>*1</sup>	P <sub>C</sub>	130	mW
	Isolation Voltage <sup>*2</sup>	BV	2 500	Vr.m.s.
Operating Ambient Temperature		T <sub>A</sub>	−40 to +85	°C
Storage Temperature		T <sub>stg</sub>	−55 to +125	°C

\*1 T<sub>A</sub> = −40 to +85°C

\*2 AC voltage for 1 minute at T<sub>A</sub> = 25°C, RH = 60% between input and output.

**RECOMMENDED OPERATING CONDITIONS**

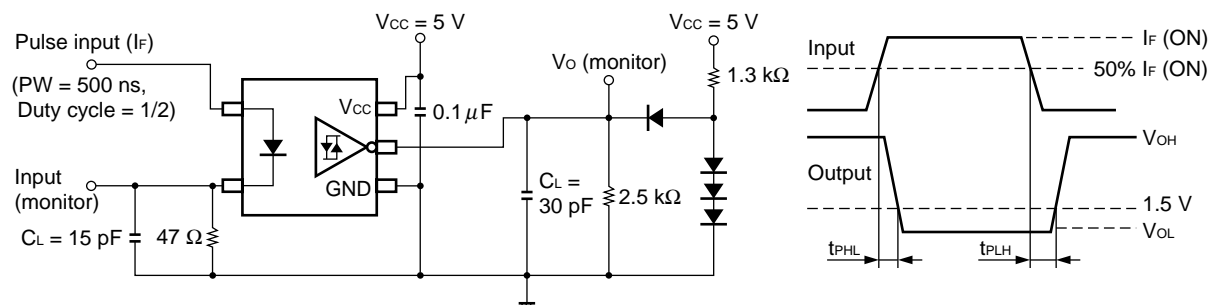
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
High Level Input Current	I <sub>FH</sub>	7.5		12.5	mA
Low Level Input Current	I <sub>FL</sub>	0		250	μA
Supply Voltage	V <sub>CC</sub>	4.5	5.0	5.5	V
TTL (loads)	N			3	

**ELECTRICAL CHARACTERISTICS ( $T_A = -40$  to  $+85^\circ\text{C}$ , unless otherwise specified)**

Parameter		Symbol	Conditions	MIN.	TYP. <sup>1)</sup>	MAX.	Unit
Diode	Forward Voltage	$V_F$	$I_F = 10\text{ mA}$ , $T_A = 25^\circ\text{C}$	1.4	1.65	1.9	V
	Reverse Current	$I_R$	$V_R = 3\text{ V}$ , $T_A = 25^\circ\text{C}$			10	$\mu\text{A}$
	Terminal Capacitance	$C_t$	$V = 0\text{ V}$ , $f = 1\text{ MHz}$ , $T_A = 25^\circ\text{C}$		30		pF
Detector	High Level Output Current	$I_{OH}$	$V_{CC} = V_O = 5.5\text{ V}$ , $I_F = 250\text{ }\mu\text{A}$		1	200	$\mu\text{A}$
	High Level Output Voltage	$V_{OH}$	$V_{CC} = 4.5\text{ V}$ , $I_F = 250\text{ }\mu\text{A}$ , $I_{OH} = -2\text{ mA}$	2.4	3.0		V
	Low Level Output Voltage	$V_{OL}$	$V_{CC} = 4.5\text{ V}$ , $I_F = 7\text{ mA}$ , $I_{OL} = 8\text{ mA}$		0.38	0.6	V
	High Level Supply Current	$I_{CCH}$	$V_{CC} = 5.5\text{ V}$ , $I_F = 0\text{ mA}$		11	17	mA
	Low Level Supply Current	$I_{CCL}$	$V_{CC} = 5.5\text{ V}$ , $I_F = 10\text{ mA}$		12	18	mA
	High Level Output Short Circuit Current	$I_{OSH}$	$V_{CC} = 5.5\text{ V}$ , $V_O = \text{GND}$ , $I_F = 0\text{ mA}$ , 10 ms or less		-26		mA
	Low Level Output Short Circuit Current	$I_{OSL}$	$V_{CC} = V_O = 5.5\text{ V}$ , $I_F = 8\text{ mA}$ , 10 ms or less		34		mA
Coupled	Threshold Input Current (H $\rightarrow$ L)	$I_{FHL}$	$V_{CC} = 5\text{ V}$ $T_A = 25^\circ\text{C}$		2.0	5	mA
						6	
	Threshold Input Current (L $\rightarrow$ H)	$I_{FLH}$	$V_{CC} = 5\text{ V}$ $T_A = 25^\circ\text{C}$	0.5			mA
				0.35			
	Isolation Resistance	$R_{I-O}$	$V_{I-O} = 1\text{ kV}_{DC}$ , $R_H = 40$ to $60\%$ , $T_A = 25^\circ\text{C}$	$10^{11}$			$\Omega$
	Isolation Capacitance	$C_{I-O}$	$V = 0\text{ V}$ , $f = 1\text{ MHz}$ , $T_A = 25^\circ\text{C}$		0.4		pF
	Propagation Delay Time (H $\rightarrow$ L) <sup>2</sup>	$t_{PHL}$	$T_A = 25^\circ\text{C}$	15	30	65	ns
			$V_{CC} = 5\text{ V}$ , $I_F = 7.5\text{ mA}$	10		85	
	Propagation Delay Time (L $\rightarrow$ H) <sup>2</sup>	$t_{PLH}$	$T_A = 25^\circ\text{C}$	15	35	65	ns
			$V_{CC} = 5\text{ V}$ , $I_F = 7.5\text{ mA}$	10		85	
	Pulse Width Distortion (PWD) <sup>2</sup>	$ t_{PHL}-t_{PLH} $	$V_{CC} = 5\text{ V}$ , $I_F = 7.5\text{ mA}$		7	35	ns
	Common Mode Transient Immunity at High Level Output <sup>3</sup>	$CM_H$	$V_{CC} = 5\text{ V}$ , $T_A = 25^\circ\text{C}$ , $I_F = 0\text{ mA}$ , $V_{O(MIN.)} = 2\text{ V}$ , $V_{CM} = 100\text{ V}$	1	10		kV/ $\mu\text{s}$
	Common Mode Transient Immunity at Low Level Output <sup>3</sup>	$CM_L$	$V_{CC} = 5\text{ V}$ , $T_A = 25^\circ\text{C}$ , $I_F = 7.5\text{ mA}$ , $V_{O(MAX.)} = 0.8\text{ V}$ , $V_{CM} = 100\text{ V}$	1	10		kV/ $\mu\text{s}$

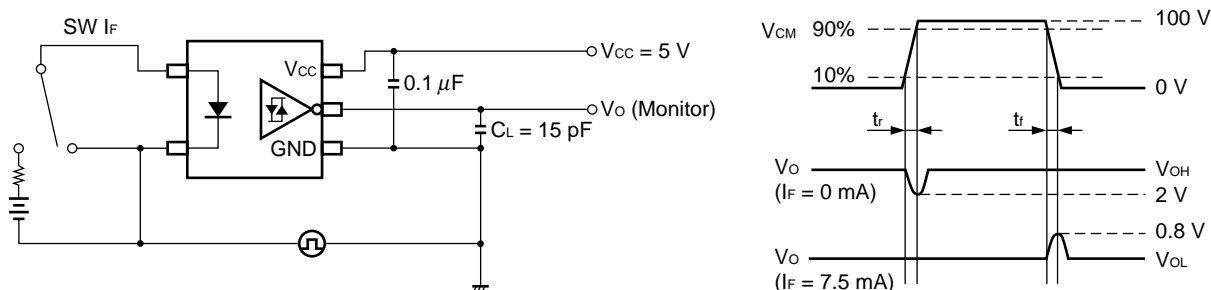
\*1 Typical values at  $T_A = 25^\circ\text{C}$

\*2 Test circuit for propagation delay time



$C_L$  includes probe and stray wiring capacitance.

★ \*3 Test circuit for common mode transient immunity



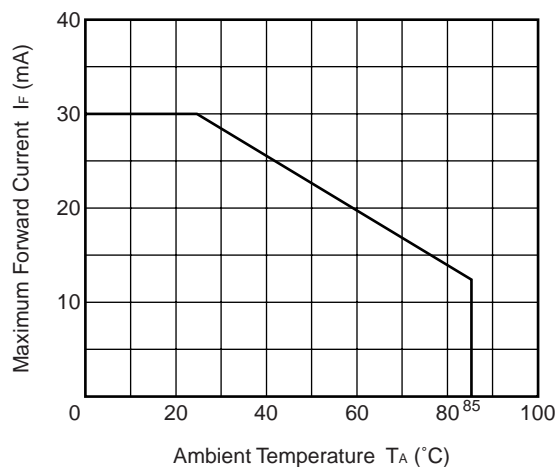
$C_L$  includes probe and stray wiring capacitance.

## USAGE CAUTIONS

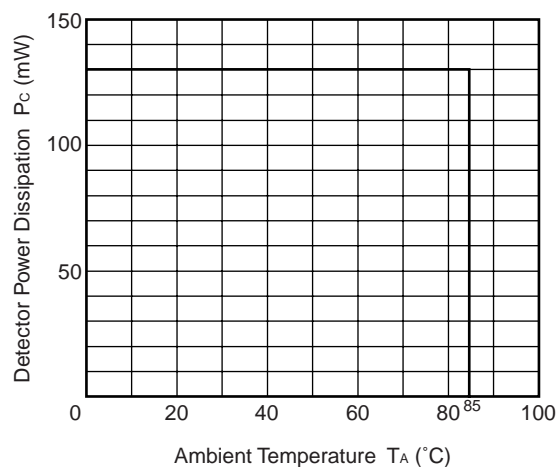
1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
- ★ 2. By-pass capacitor of more than  $0.1\text{ }\mu\text{F}$  is used between  $V_{CC}$  and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than  $10\text{ mm}$ .

**TYPICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)**

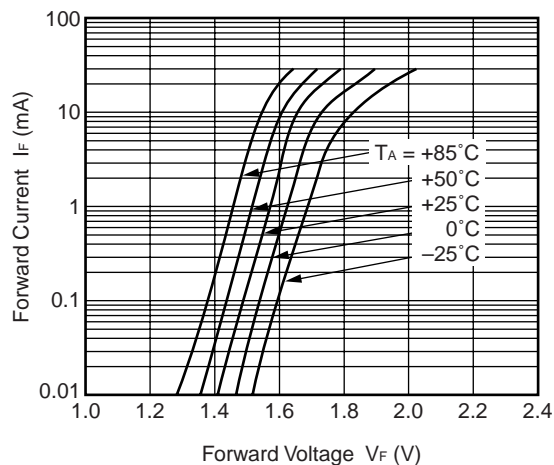
**MAXIMUM FORWARD CURRENT  
vs. AMBIENT TEMPERATURE**



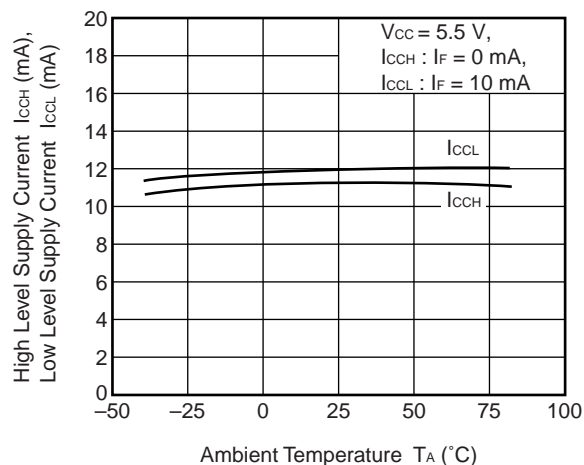
**DETECTOR POWER DISSIPATION  
vs. AMBIENT TEMPERATURE**



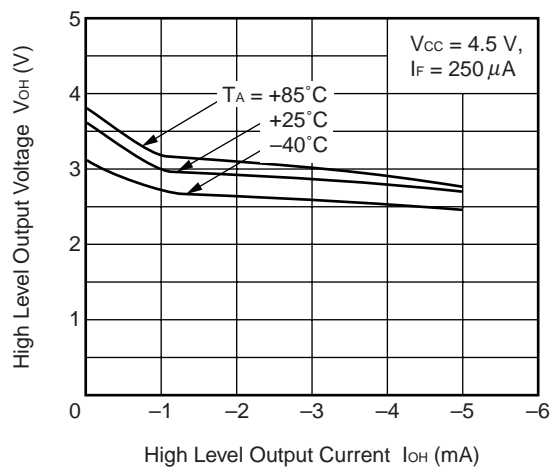
**FORWARD CURRENT vs.  
FORWARD VOLTAGE**



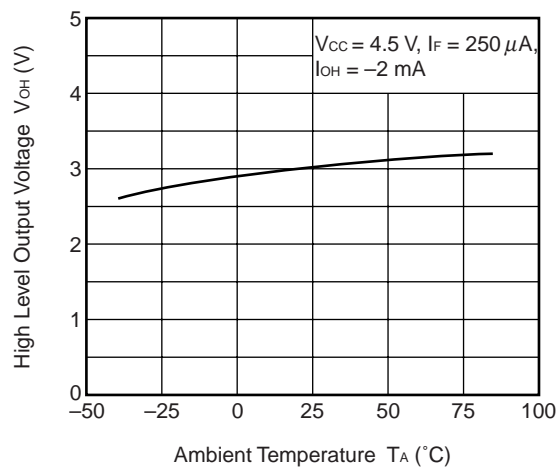
**SUPPLY CURRENT vs.  
AMBIENT TEMPERATURE**



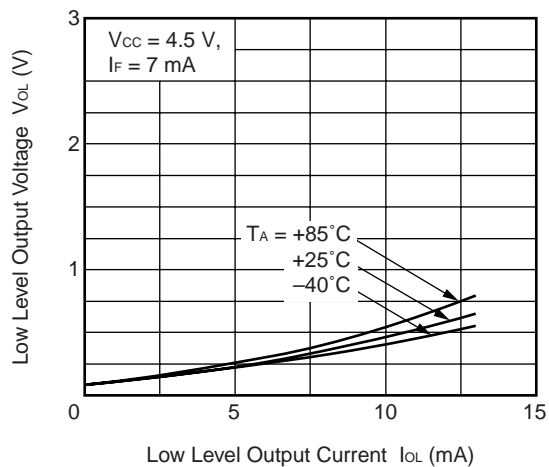
**HIGH LEVEL OUTPUT VOLTAGE vs.  
HIGH LEVEL OUTPUT CURRENT**



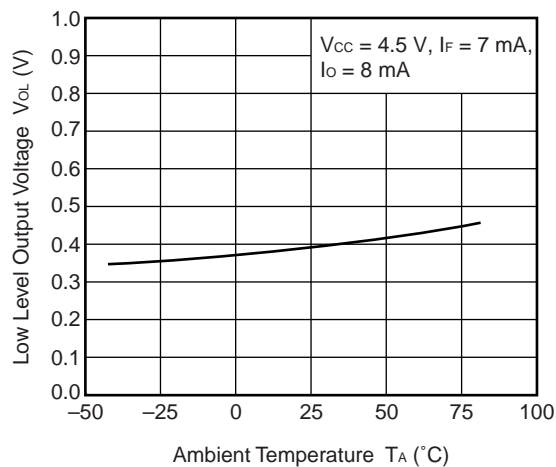
**HIGH LEVEL OUTPUT VOLTAGE vs.  
AMBIENT TEMPERATURE**



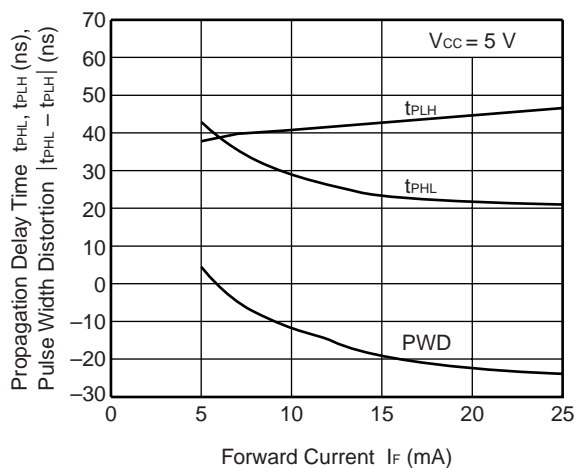
LOW LEVEL OUTPUT VOLTAGE vs.  
LOW LEVEL OUTPUT CURRENT



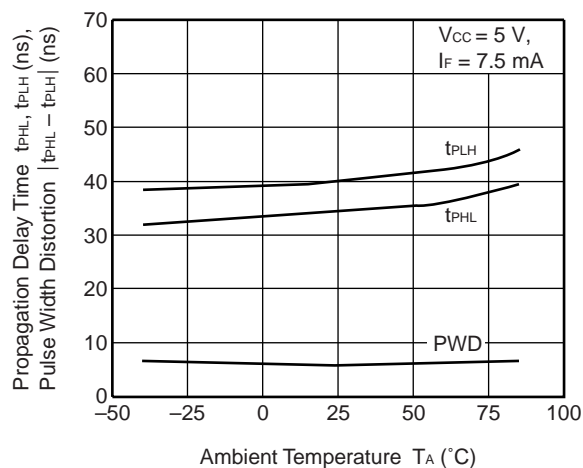
LOW LEVEL OUTPUT VOLTAGE vs.  
AMBIENT TEMPERATURE



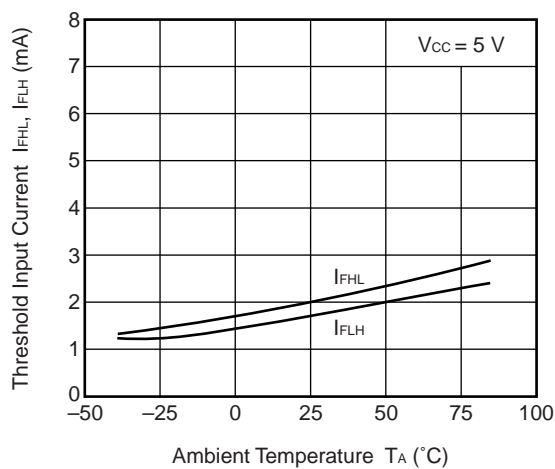
PROPAGATION DELAY TIME,  
PULSE WIDTH DISTORTION  
vs. FORWARD CURRENT



PROPAGATION DELAY TIME,  
PULSE WIDTH DISTORTION  
vs. AMBIENT TEMPERATURE



THRESHOLD INPUT CURRENT vs.  
AMBIENT TEMPERATURE

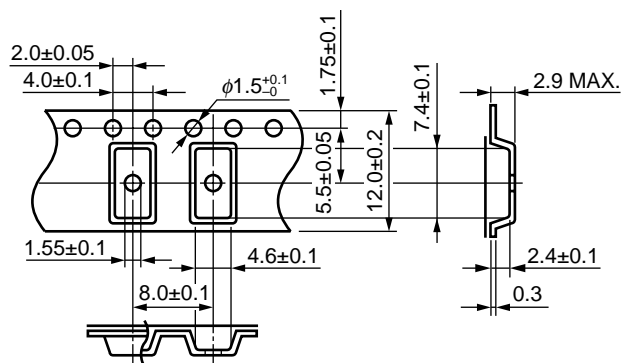


**Remark** The graphs indicate nominal characteristics.

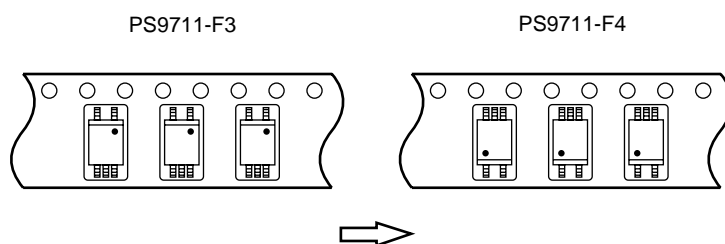


★ TAPING SPECIFICATIONS (UNIT: mm)

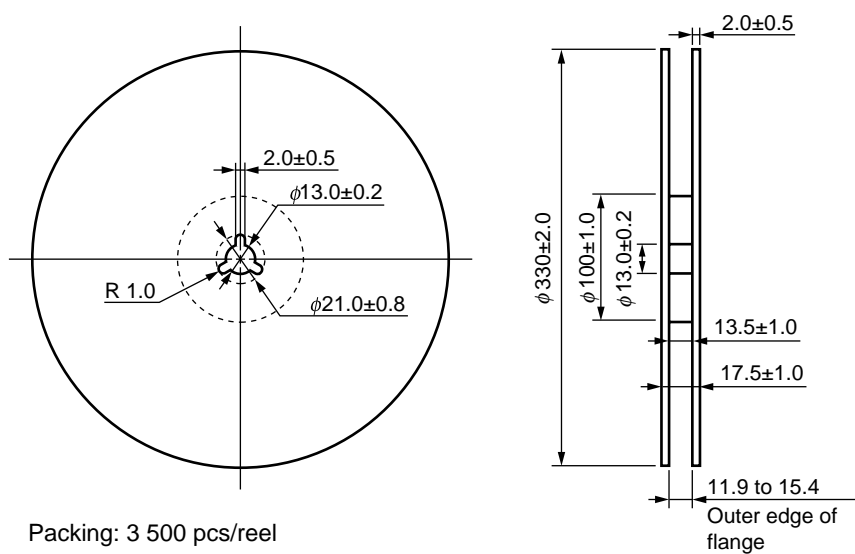
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)

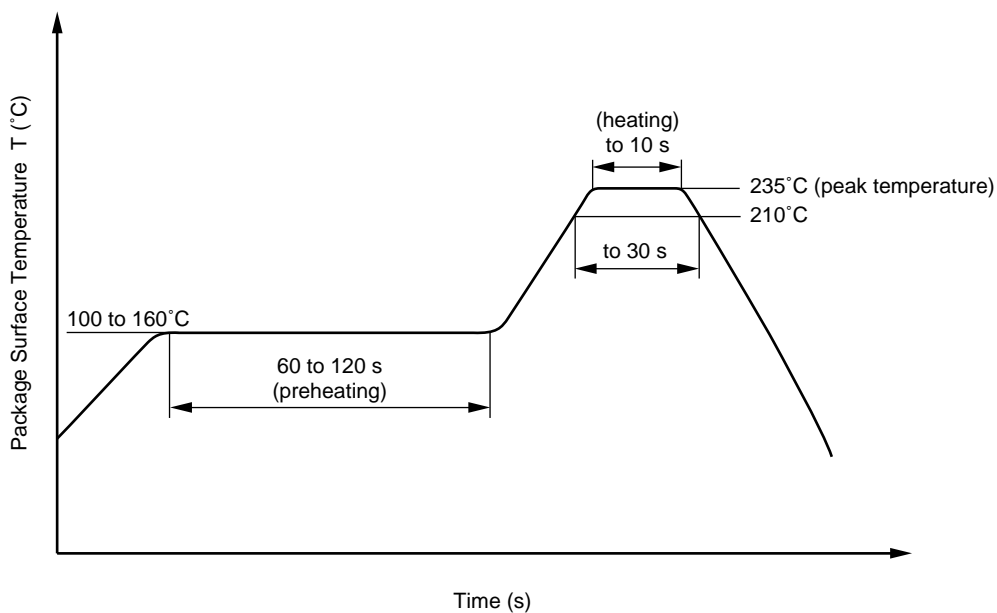


★ **RECOMMENDED SOLDERING CONDITIONS**

**(1) Infrared reflow soldering**

- |   |  |
|---|--|
| • Peak reflow temperature               | 235°C or below (package surface temperature)   |
| • Time of temperature higher than 210°C | 30 seconds or less   |
| • Number of reflows                     | Three  |
| • Flux                                  | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

Recommended Temperature Profile of Infrared Reflow



**(2) Cautions**

- Fluxes  
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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M8E 00.4-0110

**SAFETY INFORMATION ON THIS PRODUCT**

<div data-bbox="188 277 280 304" data-label="Section-Header"> <p><b>Caution</b></p> </div> <div data-bbox="300 277 448 300" data-label="Text"> <p>GaAs Products</p> </div>	<p>The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested.</p> <ul style="list-style-type: none"> <li>• Do not destroy or burn the product.</li> <li>• Do not cut or cleave off any part of the product.</li> <li>• Do not crush or chemically dissolve the product.</li> <li>• Do not put the product in the mouth.</li> </ul> <p>Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.</p>
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► **Business issue**

**NEC Compound Semiconductor Devices, Ltd.**

5th Sales Group, Sales Division TEL: +81-3-3798-6372 FAX: +81-3-3798-6783 E-mail: salesinfo@csd-nec.com

**NEC Compound Semiconductor Devices Hong Kong Limited**

Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309  
Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859  
Korea Branch Office TEL: +82-2-528-0301 FAX: +82-2-528-0302

**NEC Electron Devices European Operations** <http://www.nec.de/>

TEL: +49-211-6503-101 FAX: +49-211-6503-487

**California Eastern Laboratories, Inc.** <http://www.cel.com/>

TEL: +1-408-988-3500 FAX: +1-408-988-0279

► **Technical issue**

**NEC Compound Semiconductor Devices, Ltd.** <http://www.csd-nec.com/>

Sales Engineering Group, Sales Division  
E-mail: techinfo@csd-nec.com FAX: +81-44-435-1918